CHIPS JOINT UNDERTAKING

Anton Chichkov,

Chips JU Head of Programmes and Communications

4 Dec 2025

FUNDING ECS INNOVATION IN EUROPE

Electronic Components and Systems

September 2023

1. Strengthen Europe's research and technology leadership towards smaller and faster chips

2. Build and reinforce capacity to innovate in the design, manufacturing and packaging of advanced chips

…

4. Address the skills shortage, attract new talent and support the emergence of a skilled workforce

KDT JU
KEY DIGITAL TECHNOLOGIES JOINT UNDERTAKING

Chips JU

ECSEL JU

eniac JOINT UNDERTAKING

Nanoelectronics:
2.86 B€ costs

ARTEMIS

Embedded Systems
1.34 B€ costs

Electronic Comp & Systems:
4.69 B€ costs

Electronic Comp & Systems:
1.3 B€ EU funding

Chips for Europe Initiative:
2.8 B€ EU funding

2008 · 2014 · 2021 · 2023 · 2028

Chips JU

A One-Of-a-Kind Partnership for EU Chips Industry

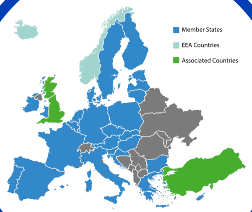
TRI-PARTITE STRUCTURE

~ € 11 Bn

European Union	Participating States	Private Members
€ 4.175 Bn	**€ 4.175 Bn**	**€ 2.500 Bn**

A ONE-OF-A-KIND PARTNERSHIP FOR EUROPE'S CHIPS INDUSTRY

TRI-PARTITE REPRESENTATION



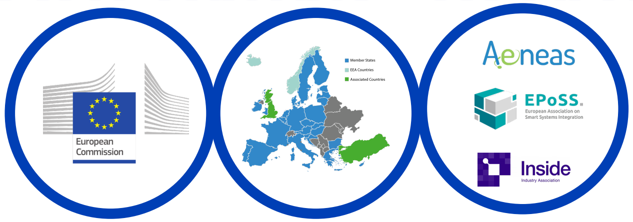
European Union
European Commission

Participating States
Public Authorities

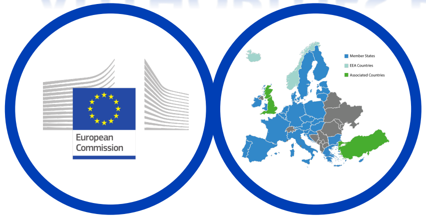
Private Members
Industry Associations

CHIPS-JU GOVERNANCE

GOVERNING BOARD



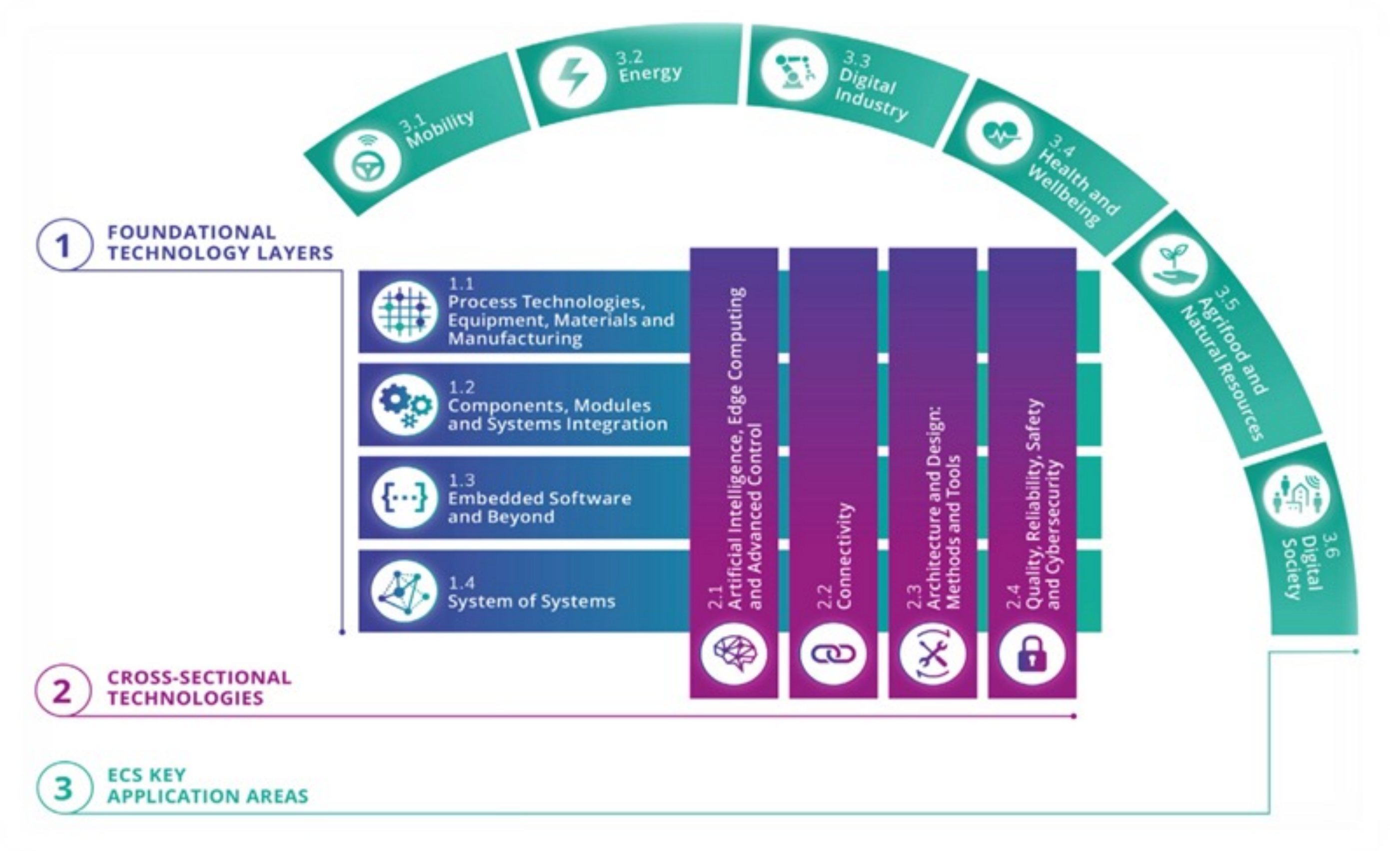
PUBLIC AUTHORITIES BOARD



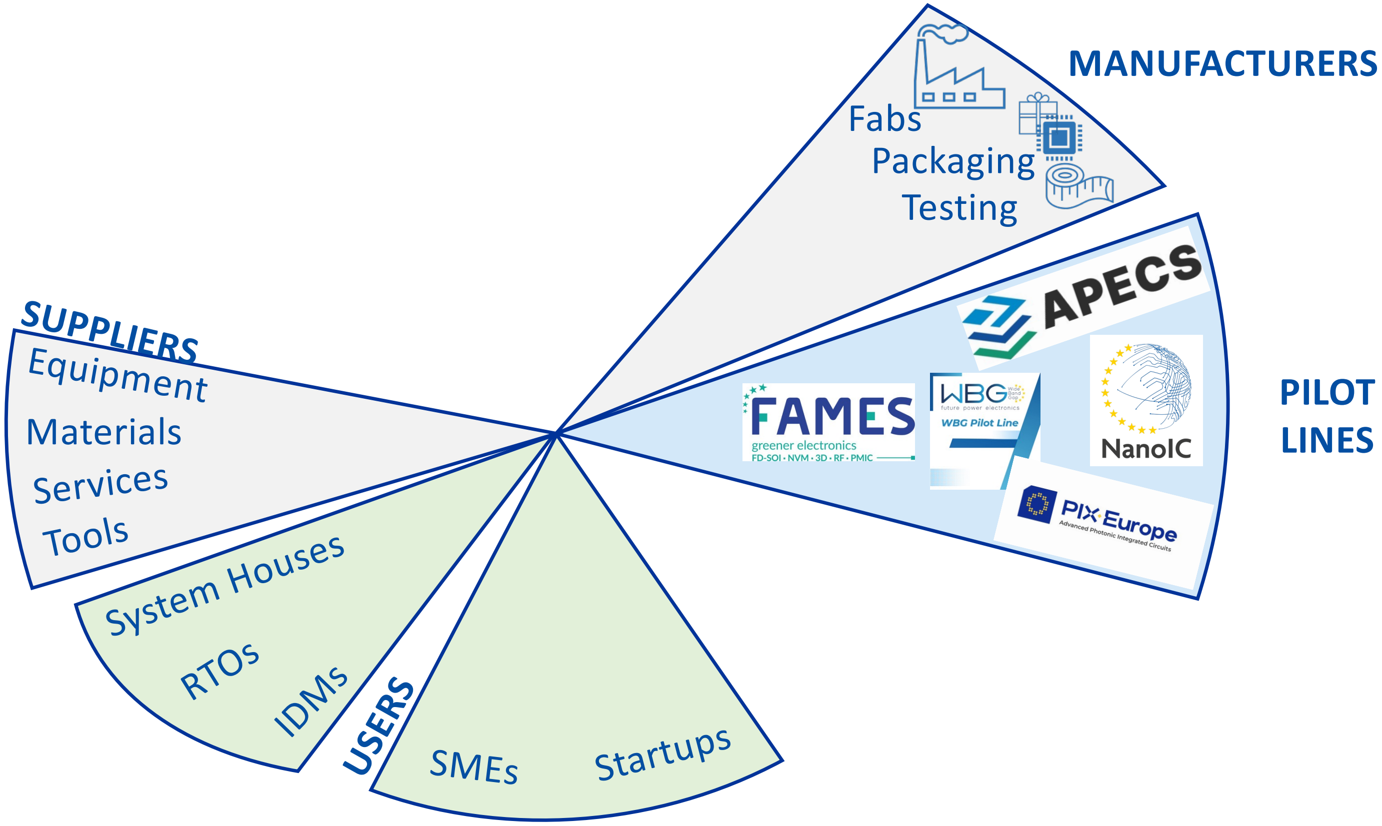
EXECUTIVE DIRECTOR

EXECUTIVE OFFICE

ELECTRONIC COMPONENTS AND SYSTEMS



CHIPS FOR EUROPE INITIATIVE PILOT LINES



MANUFACTURERS

Fabs
Packaging
Testing

PILOT LINES

APECS
FAMES greener electronics FD-SOI · NVM · 3D · RF · PMIC
WBG future power electronics WBG Pilot Line
NanoIC
PIX Europe Advanced Photonic Integrated Circuits

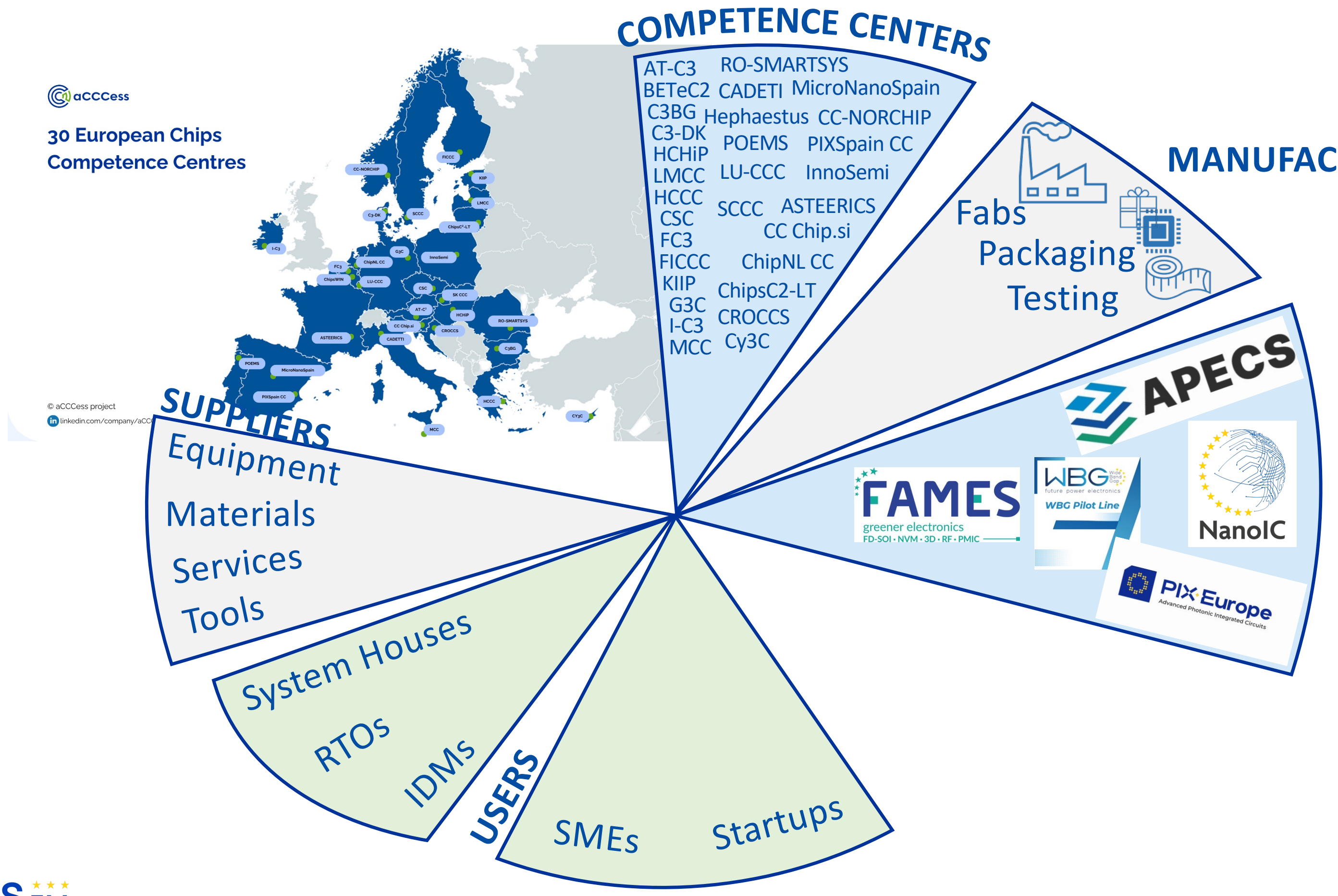
SUPPLIERS

Equipment
Materials
Services
Tools

USERS

System Houses
RTOs
IDMs
SMEs
Startups

CHIPS FOR EUROPE INITIATIVE COMPETENCE CENTERS



COMPETENCE CENTERS

AT-C3 RO-SMARTSYS
BETeC2 CADETI MicroNanoSpain
C3BG Hephaestus CC-NORCHIP
C3-DK POEMS PIXSpain CC
HCHiP
LMCC LU-CCC InnoSemi
HCCC SCCC ASTEERICS
CSC CC Chip.si
FC3
FICCC ChipNL CC
KIIP ChipsC2-LT
G3C CROCCS
I-C3 Cy3C
MCC

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NanoIC
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SUPPLIERS

Equipment
Materials
Services
Tools

USERS

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RTOs
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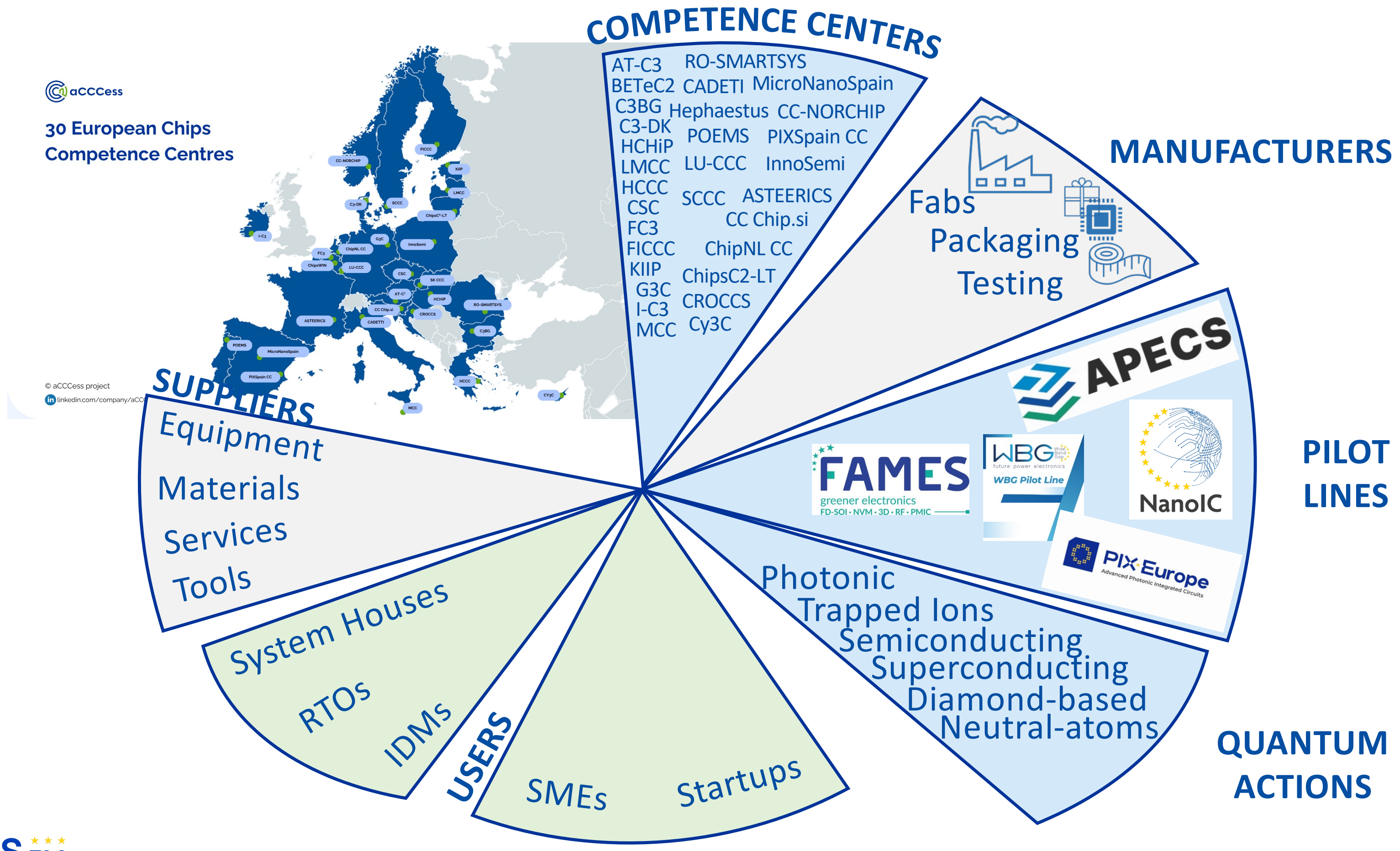
CHIPS FOR EUROPE INITIATIVE QUANTUM ACTIONS



30 European Chips Competence Centres

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linkedin.com/company/aCC

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MCC Cy3C

MANUFACTURERS

Fabs
Packaging
Testing

PILOT LINES

QUANTUM ACTIONS

Photonic
Trapped Ions
Semiconducting
Superconducting
Diamond-based
Neutral-atoms

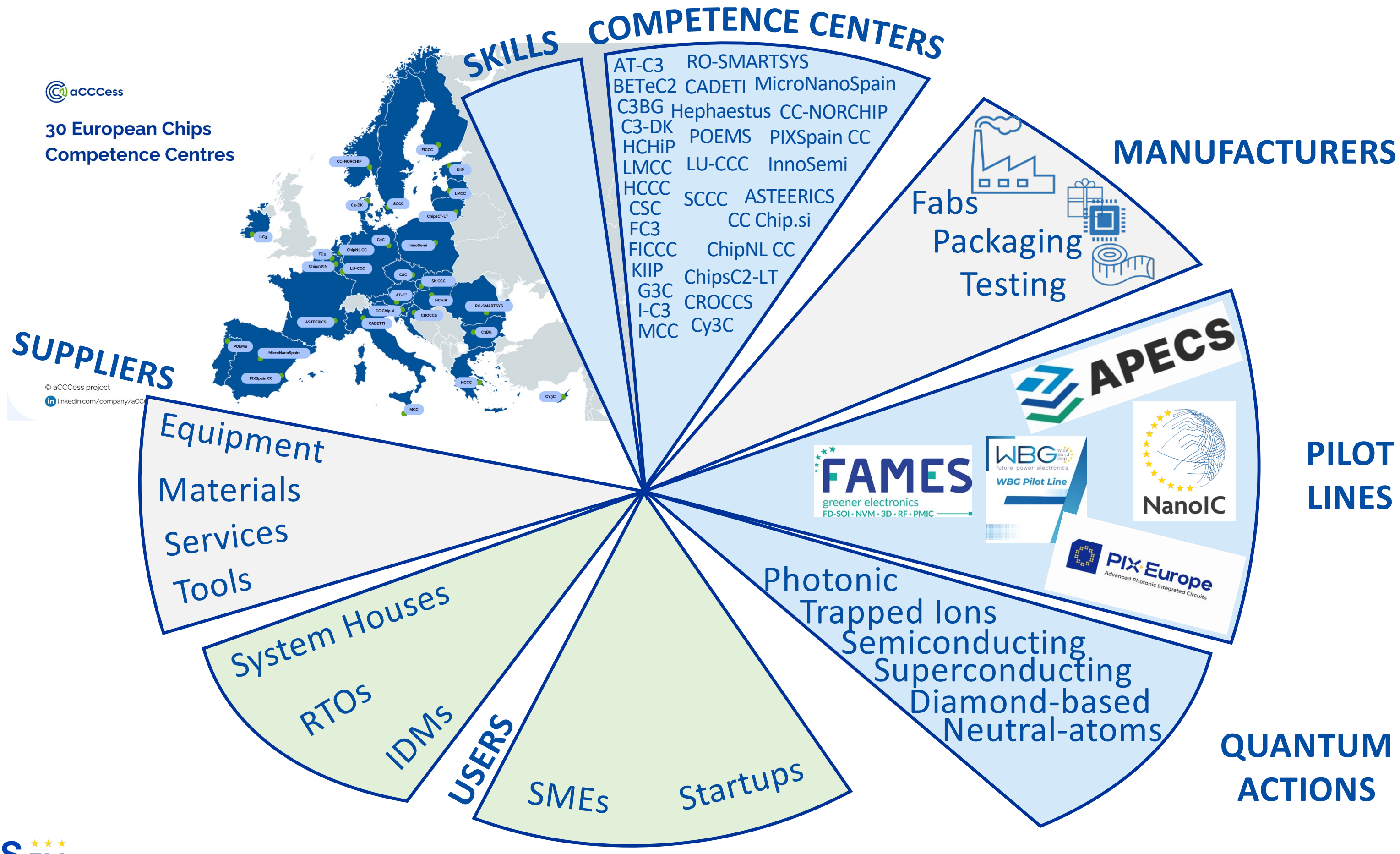
USERS

SMEs
Startups
System Houses
RTOs
IDMs

SUPPLIERS

Equipment
Materials
Services
Tools

CHIPS FOR EUROPE INITIATIVE SKILLS



aCCCess

30 European Chips Competence Centres

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SKILLS

COMPETENCE CENTERS

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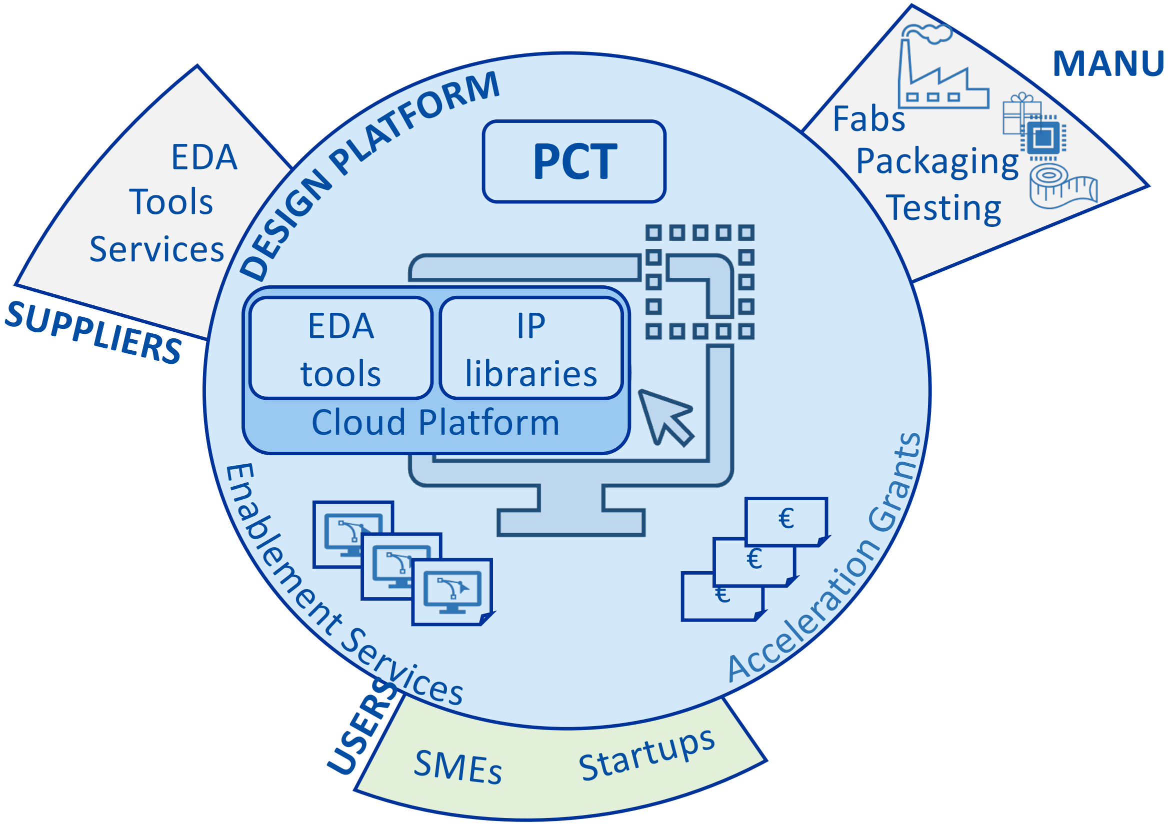
IDMs

SUPPLIERS

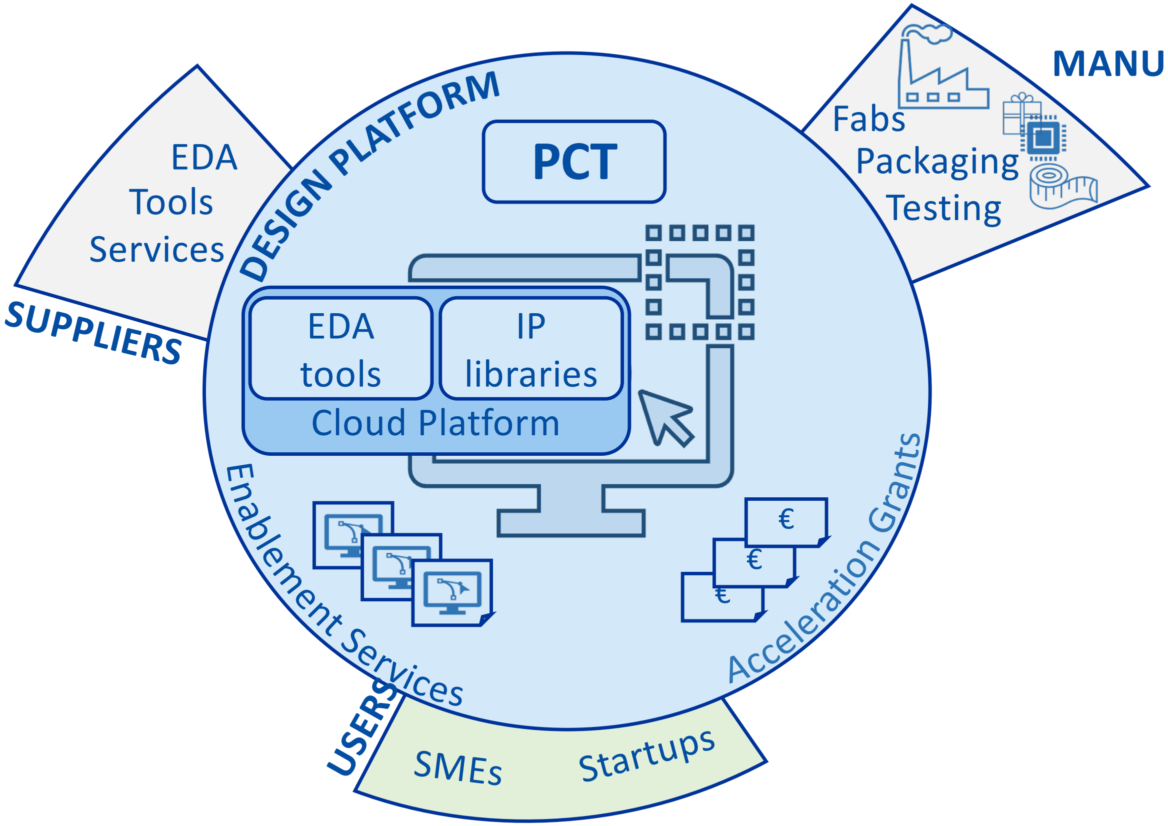
Equipment
Materials
Services
Tools

ChipsJU

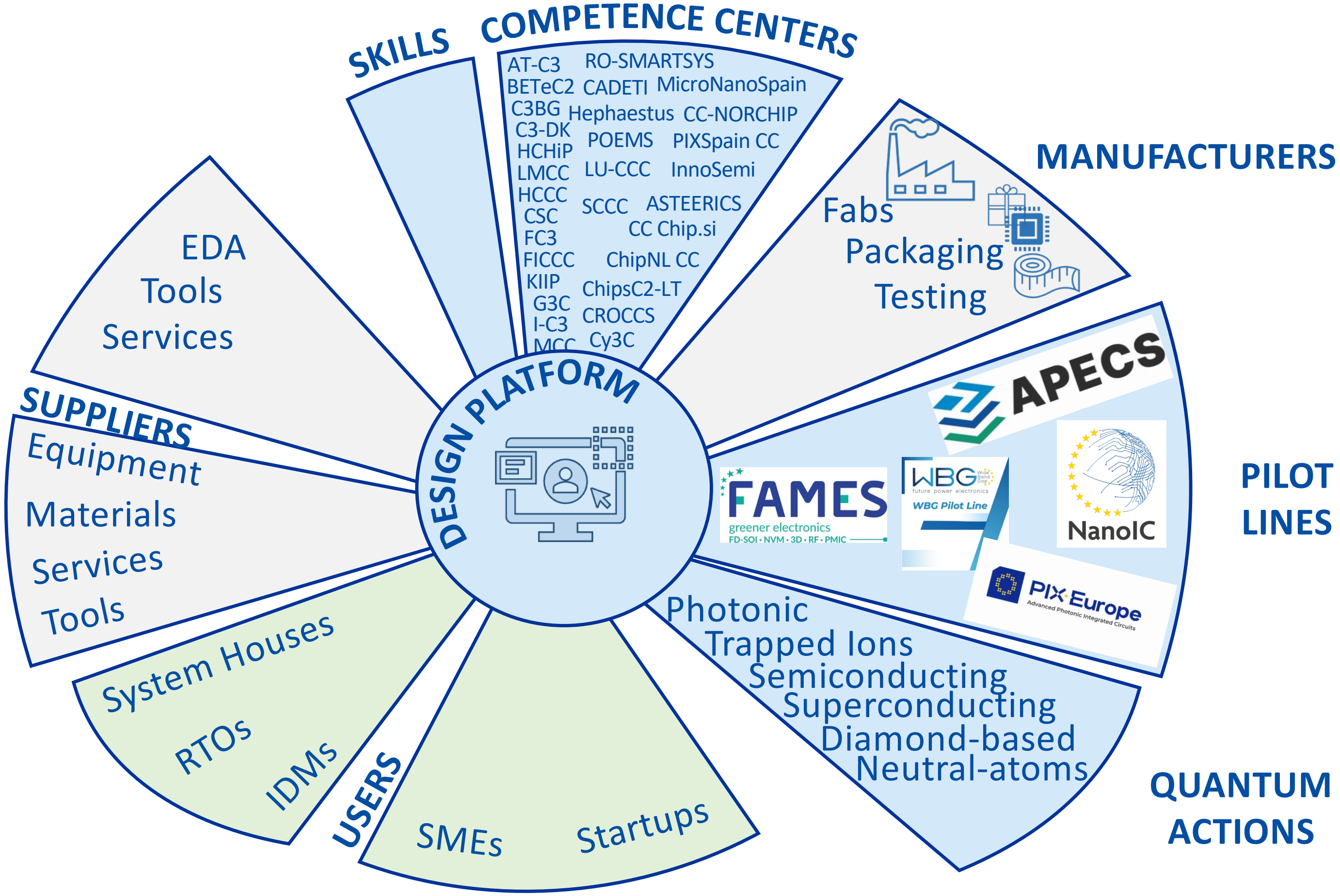
CHIPS FOR EUROPE INITIATIVE DESIGN PLATFORM



CHIPS FOR EUROPE INITIATIVE DESIGN PLATFORM



CHIPS FOR EUROPE INITIATIVE



DESIGN PLATFORM

SKILLS

COMPETENCE CENTERS

AT-C3 RO-SMARTSYS
BETeC2 CADETI MicroNanoSpain
C3BG Hephaestus CC-NORCHIP
C3-DK POEMS PIXSpain CC
HCHiP
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PILOT LINES

QUANTUM ACTIONS

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USERS

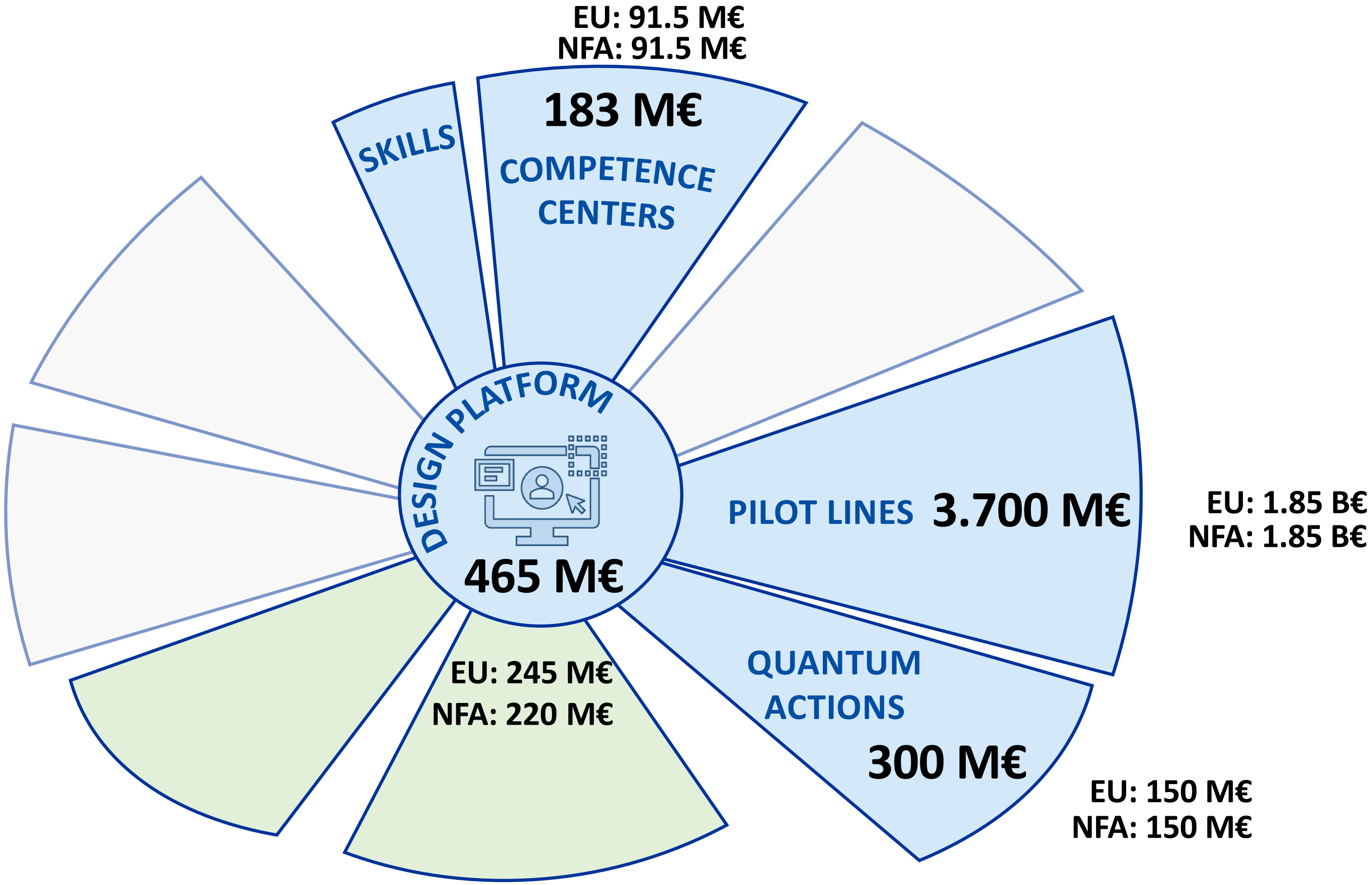
SMEs Startups
System Houses
RTOs
IDMs

SUPPLIERS

Equipment
Materials
Services
Tools

EDA
Tools
Services

CHIPS FOR EUROPE INITIATIVE



EU: 91.5 M€
NFA: 91.5 M€

183 M€
COMPETENCE CENTERS

SKILLS

DESIGN PLATFORM
465 M€

EU: 245 M€
NFA: 220 M€

PILOT LINES 3.700 M€

EU: 1.85 B€
NFA: 1.85 B€

QUANTUM ACTIONS
300 M€

EU: 150 M€
NFA: 150 M€

STATE OF PLAY

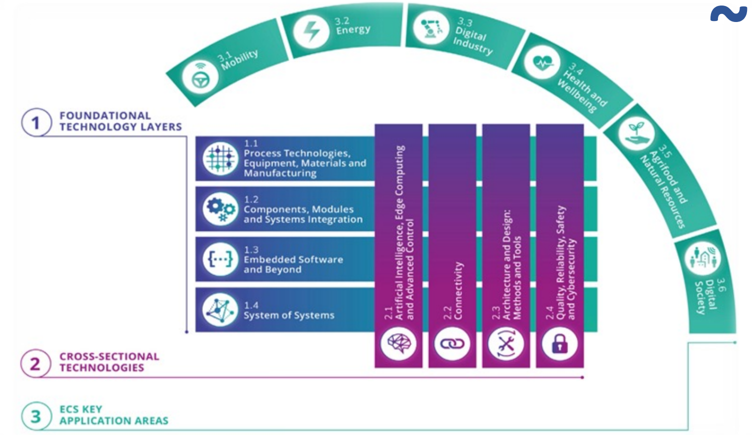
1.3 BN

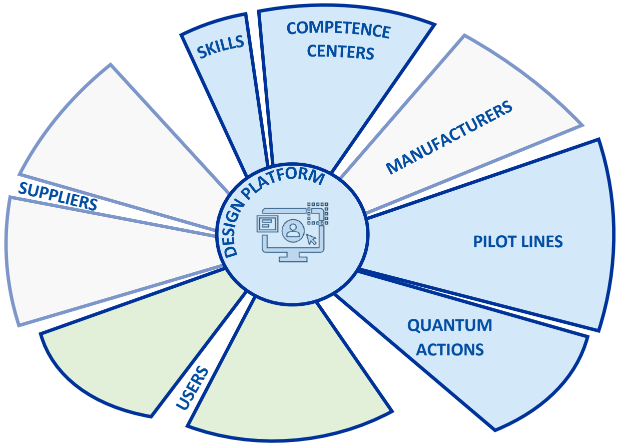
Electronic Components and Systems

2.875 BN

Chips for Europe Initiative

~ € 4.175 BN





~92%

~1.037 M€

~2.369 M€

EVALUATION PROCESS

Anton Chichkov,
Chips JU Head of Programmes and Communications

4 Dec 2025

PO Stage Assessment

- Purpose
  - Collect initial information about partners and budgets
  - Give initial feedback of independent reader to allow improvements
  - Eliminate out of scope and immature proposals to save effort in proposal preparation and proposal evaluation
- Reduced Proposal
  - Only part of the Excellence (Methodology is not required)
  - Only part of the Impact (Measures to maximise expected outcomes and impacts is not required)
  - Very minimal part of the Implementation
- 3 experts assess each proposal
- No ranking

FPP Stage Evaluation

- Purpose
  - Produce fair ranking of proposals according to the predefined criteria
- Full Proposal
- 4 experts fully evaluate the proposal
- 3 experts cross read the proposal
- Blind calibration by sub-panels per criteria (1/3 of the experts)
- Reassessment of the sub-panels suggestion by the team of evaluators
- Final ranking decided in full panel of all experts
  - Detailed discussion and comparison of each proposal to establish correct place in the ranking

EVALUATION RESULTS ECS CALLS 2025

Anton Chichkov,
Chips JU Head of Programmes and Communications

4 Dec 2025

FINAL RANKING GLOBAL IA

Rank	Acronym	Rank	Acronym
1	Moore4Power	10	DTOP5
2	TREASURY	11	FA4EU
3	GreenFab-X	12	MONITOR
4	CONNECTINGCHIPS	13	GOWIRELESS
5	INSPIRED	14	CHIPMUNC
6	IMPHORIA	15	DAICES
7	ORIONN	16	CASCADE
8	SPECS	17	Proper 2
9	GaN4EU	18	TRUSTWISE

Proposals
Smart Food Cain and DRONEAI
were placed under the
threshold by the expert panel
and are not part of the PAB
ranking

GLOBAL IA PROPOSALS RETAINED FOR FUNDING

Rank	Acronym
1	Moore4Power
2	TREASURY
3	GreenFab-X

GLOBAL IA PROPOSALS ON THE RESERVE LIST

Rank	Acronym
4	CONNECTINGCHIPS
5	INSPIRED
6	IMPHORIA

FINAL RANKING IA FT1 AND IA FT2

IIA FT1

Rank	Acronym
1	TURANDOT

IIA FT2

Rank	Acronym
1	AI4SDV

IA FT1 AND IA FT2 RETAINED FOR FUNDING

IIA FT1

Rank	Acronym
1	TURANDOT

There were no proposals retained for funding in IA FT2 due to lack of adequate national funding

FINAL RANKING GLOBAL RIA

Rank	Acronym	Rank	Acronym
1	uPQComing	14	CIRCLE
2	HumAMI	15	OOvFPGASIC
3	CIRES	16	PANEPOPTIS
4	SPIN CHIP	17	ADACHIPS
5	AIDOSec	18	iALTEREGO
6	AFarEdge	19	APOQCRYF
7	HEMISYS	20	SHIELD
8	HANNA	21	HumanSyS
9	SURPRISE4EU	22	EDGEWISE
10	MINIRAMA	23	PLANT-AID
11	SafeHealth	24	QUAI
12	CHIPMUNK	25	XIVOCS
13	TRANSCEND	26	GenAI4ECS

Proposals
QUAI, XIVOCS and GenAI4ECS were placed under the threshold by the expert panel and are not part of the PAB ranking

GLOBAL RIA PROPOSALS RETAINED FOR FUNDING

Rank	Acronym
1	uPQComing
2	HumAMI
3	CIRES
4	SPIN CHIP

GLOBAL RIA PROPOSALS ON THE RESERVE LIST

Rank	Acronym
5	AIDOSec
6	AFarEdge
7	HEMISYS

FINAL RANKING QUANTUM SGA

Call	Rank	Acronym
QAC1-1	1	SUPREME 1
QAC1-2	1	P4Q
QAC1-3	1	SPINS SGA1
QAC1-4	1	DIREQT
QAC1-5	1	Q-PLANET SGA1
QAC2-1	1	CHAMP-ION SGA1

QUANTUM SGA PROPOSALS RETAINED FOR FUNDING

Call	Rank	Acronym
QAC1-1	1	SUPREME 1
QAC1-2	1	P4Q
QAC1-3	1	SPINS SGA1
QAC1-4	1	DIREQT
QAC1-5	1	Q-PLANET SGA1
QAC2-1	1	CHAMP-ION SGA1

FINAL RANKING EDA

Rank	Acronym
1	ODE4EC-AMS
2	ODE4EC-DIG
3	ODE4EC-PIV

EDA PROPOSALS RETAINED FOR FUNDING

Rank	Acronym
1	ODE4EC-AMS
2	ODE4EC-DIG
3	ODE4EC-PIV

CHIPS JU CALLS AND ACTIONS 2026

Anton Chichkov,
Chips JU Head of Programmes and Communications

4 Dec 2025

ELECTRONIC COMPONENTS AND SYSTEMS

- GLOBAL – RIA
  Bottom-up call according to SRIA 2026
- FT RIA - 6G Front End Module
- RIA International collaboration call –
  Call with Digital Partnership and TTC countries

- GLOBAL IA
  Bottom-up call according to SRIA 2026
- FT - IA Healthcare
- FT - IA Power Electronics
- FT - IA Photonics
- Coordination of the European software-defined vehicle platform – CSA
- Supply chain resilience - CSA

This is preliminary information!

There is no GB decision on Chips JU WP2026.

Topics can be dropped out of this list, and other topics can be included!

ELECTRONIC COMPONENTS AND SYSTEMS

Topic	**Programme**	**Type of Action**	**Budget M€**
Open RIA	HE	RIA	50
FT RIA-6G	HE	RIA	20
Joint call with Dig Part TTC countries	HE	RIA	5
Open IA	HE	IA	40
FT IA-Power	HE	IA	20
FT IA-Photonics	HE	IA	20
FT IA-Health	HE	IA	20
Next Generation SDV Ecosystem	HE	CSA	2
Suply chain resilience	HE	CSA	2
Total			179

This is preliminary information!

There is no GB decision on Chips JU WP2026.

Budgets can be changed!

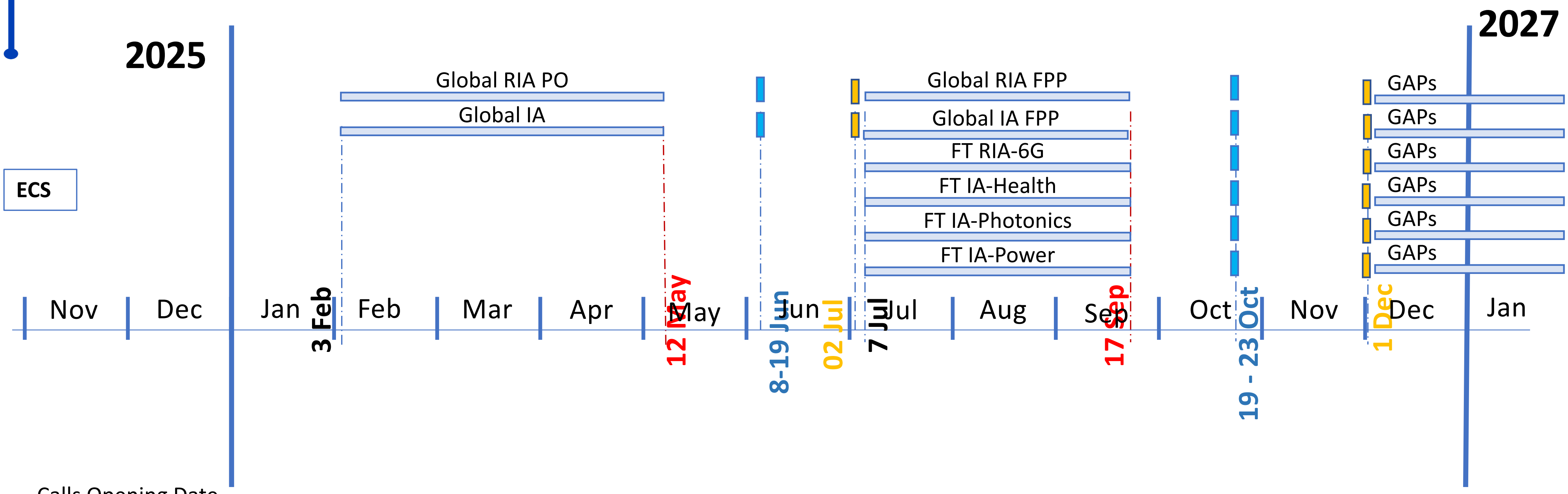
CHIPS FOR EUROPE INITIATIVE CALLS AND ACTIONS

- Call Activities
  - Quantum
  - Design Platform
  - Skills
- Other Activities
  - AI

This is preliminary information!

There is no GB decision on Chips for Europe Initiative part of the WP2026!

PLANNING CHIPS-JU ECS CALLS 2026



Calls Opening Date
Calls Deadline
🟦 Proposals Evaluation
🟨 PAB Dec
🟩 PAB Amended Funding Dec

This is preliminary information!

Some Schedules can be changed!

ECS Brokerage Event 2026

ECS BROKERAGE EVENT 2026

4 & 5 February
The EGG, Brussels

INFO & REGISTRATION:
https://ecs-brokerage-event.eu/